

+2.7V to +5.5V, Low-Power, Dual, Parallel 8-Bit DAC with Rail-to-Rail Voltage Outputs

General Description

The MAX5102 parallel-input, voltage-output, dual 8-bit digital-to-analog converter (DAC) operates from a single +2.7V to +5.5V supply and comes in a space-saving 16-pin TSSOP package. Internal precision buffers swing Rail-to-Rail®, and the reference input range includes both ground and the positive rail. Both DACs share a common reference input.

The MAX5102 has separate input latches for each of its DACs. Data is transferred to the input latches from a common 8-bit input port. The DACs are individually selected through address input A0 and are updated by bringing \overline{WR} low.

The MAX5102 features a shutdown mode that reduces current to 1nA, as well as a power-on reset mode that resets all registers to code 00 hex on power-up.

Features

INL

(LSB)

±1

±2

- +2.7V to +5.5V Single-Supply Operation
- Ultra-Low Supply Current
 0.2mA while Operating
 1nA in Shutdown Mode

PART

MAX5102AEUE

MAX5102BEUE

- Ultra-Small 16-Pin TSSOP Package
- Ground to V_{DD} Reference Input Range
- ♦ Output Buffer Amplifiers Swing Rail-to-Rail
- Power-On Reset Sets All Registers to Zero

TEMP. RANGE

-40°C to +85°C

-40°C to +85°C

Ordering Information

PIN-PACKAGE

16 TSSOP

16 TSSOP

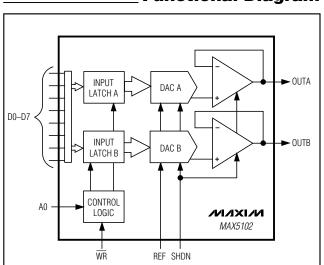
Applications

Digital Gain and Offset Adjustment

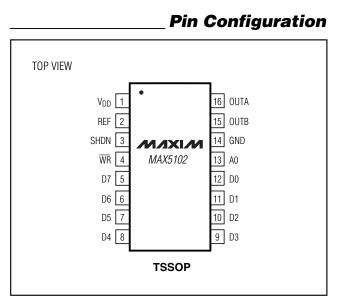
Programmable Attenuators

Portable Instruments

Power-Amp Bias Control







Rail-to-Rail is a registered trademark of Nippon Motorola, Ltd.

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ABSOLUTE MAXIMUM RATINGS

V _{DD} to GND	0.3V to +6V
D_, A0, WR, SHDN to GND	0.3V to +6V
REF to GND	0.3V to (V _{DD} + 0.3V)
OUT_ to GND	0.3V to V _{DD}
Maximum Current into Any Pin	±50mA
Continuous Power Dissipation ($T_A = +70^{\circ}$	C)
16-Pin TSSOP (derate 5.7mW/°C abov	e +70°C)457mW

Operating Temperature Range

MAX5102_EUE	40°C to +85°C
Maximum Junction Temperature	e+150°C
	65°C to +150°C
Lead Temperature (soldering, 1	0sec)+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{DD} = V_{REF} = +2.7V \text{ to } +5.5V, \text{ GND} = 0V, \text{ } \text{R}_{L} = 10 \text{k}\Omega, \text{ } \text{C}_{L} = 100 \text{p}\text{F}, \text{ } \text{T}_{A} = \text{T}_{MIN} \text{ to } \text{T}_{MAX}, \text{ unless otherwise noted}. \text{ Typical values are at } V_{DD} = V_{REF} = +3V \text{ and } \text{T}_{A} = +25^{\circ}\text{C}.)$

PARAMETER	SYMBOL	CONDITIONS		MIN	ТҮР	MAX	UNITS
STATIC ACCURACY							•
Resolution						8	Bits
Integral Naplingarity (Nato 1)	INL	MAX5102A				±1	- LSB
Integral Nonlinearity (Note 1)	IINL	MAX5102B				±2	
Differential Nonlinearity (Note 1)	DNL	Guaranteed monotoni	C			±1	LSB
Zero-Code Error	ZCE	Code = 00 hex				±20	mV
Zero-Code-Error Supply Rejection		Code = 00 hex, V _{DD} =	2.7V to 5.5V			10	mV
Zero-Code Temperature Coefficient		Code = 00 hex	Code = 00 hex		±10		µV/°C
Gain Error (Note 2)		Code = F0 hex				±1	%
Gain-Error Temperature Coefficient		Code = F0 hex			±0.001		LSB/°C
Power-Supply Rejection			$V_{DD} = 2.7V \text{ to } 3.6V,$ $V_{REF} = 2.5V$			1	
		Code = FF hex	$V_{DD} = 4.5V \text{ to } 5.5V,$ $V_{REF} = 4.096V$			1	LSB
REFERENCE INPUT	1			1			1
Input Voltage Range				0		V _{DD}	V
Input Resistance					460	600	kΩ
Input Capacitance					15		рF
DAC OUTPUTS							
Output Voltage Range		RL = ∞		0		VREF	V
DIGITAL INPUTS							
Input High Voltage	VIH	V _{DD} = 2.7V to 3.6V		2			v
	* IN	V _{DD} = 3.6V to 5.5V		3			
Input Low Voltage	VIL					0.8	V
Input Current	l _{IN}	$V_{IN} = V_{DD} \text{ or } GND$				±1.0	μA
Input Capacitance	CIN				10		pF



ELECTRICAL CHARACTERISTICS (continued)

 $(V_{DD} = V_{REF} = +2.7V \text{ to } +5.5V, \text{ GND} = 0V, \text{ R}_{L} = 10\text{k}\Omega, \text{ C}_{L} = 100\text{pF}, \text{ T}_{A} = \text{T}_{MIN} \text{ to } \text{T}_{MAX}$, unless otherwise noted. Typical values are at $V_{DD} = V_{REF} = +3V$ and $\text{T}_{A} = +25^{\circ}\text{C}$.)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
DYNAMIC PERFORMANCE			_			
Output Voltage Slew Rate		From code 00 to code F0 hex	0.6			V/µs
Output Settling Time (Note 3)		To 1/2LSB, from code 00 to code F0 hex	6			μs
Channel-to-Channel Isolation (Note 4)		Code 00 to code FF hex		500		nVs
Digital Feedthrough (Note 5)		Code 00 to code FF hex		0.5		nVs
Digital-to-Analog Glitch Impulse		Code 80 hex to code 7F hex		90		nVs
Signal-to-Noise plus Distortion Ratio	SINAD	REF = 2.5Vp-p at 1kHz, V _{REF(DC)} = 1.5V, V _{DD} = 3V, code FF hex	70			
		REF = 2.5Vp-p at 10kHz, V _{REF(DC)} = 1.5V, V _{DD} = 3V, code FF hex		60		- dB
Multiplying Bandwidth		$\begin{array}{l} REF = 0.5Vp\text{-p}, V_{REF(DC)} = 1.5V, \\ V_{DD} = 3V, -3dB bandwidth \end{array} \tag{650}$			kHz	
Wideband Amplifier Noise				60		μV _{RMS}
Shutdown Recovery Time	tSDR	To $\pm 1/2$ LSB of final value of V _{OUT}		13		μs
Time to Shutdown	t SDN	I _{DD} < 5µA		20		μs
POWER SUPPLIES						
Power-Supply Voltage	V _{DD}		2.7		5.5	V
Supply Current (Note 6)	IDD			190	360	μA
Shutdown Current				0.001	1	μA
DIGITAL TIMING (Figure 1) (Note	e 7)					
Address to WR Setup	tas		5			ns
Address to WR Hold	t _{AH}		0			ns
Data to WR Setup	t _{DS}		25			ns
Data to \overline{WR} Hold	tDH		0			ns
WR Pulse Width	twR		20			ns

Note 1: Reduced digital code range (code 00 hex to code F0 hex) due to swing limitations when the output amplifier is loaded.

Note 2: Gain error is: [100 (V_{F0,meas} - ZCE - V_{F0,ideal}) / V_{REF}]. Where V_{F0,meas} is the DAC output voltage with input code F0 hex, and V_{F0,ideal} is the ideal DAC output voltage with input code F0 hex (i.e., V_{REF} • 240 / 256).

Note 3: Output settling time is measured from the 50% point of the falling edge of WR to ±1/2LSB of V_{OUT}'s final value.

Note 4: Channel-to-channel isolation is defined as the glitch energy at a DAC output in response to a full-scale step change on any other DAC output. The measured channel has a fixed code of 80 hex.

Note 5: Digital feedthrough is defined as the glitch energy at any DAC output in response to a full-scale step change on all eight data inputs with WR at V_{DD}.

Note 6: $R_L = \infty$, digital inputs at GND or V_{DD}.

Note 7: Timing measurement reference level is $(V_{IH} + V_{IL}) / 2$.

M/X/W



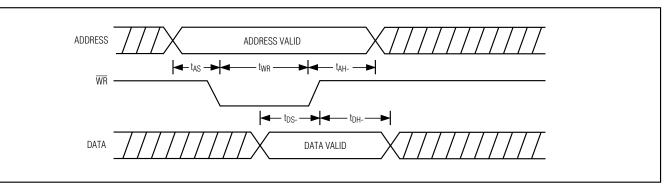
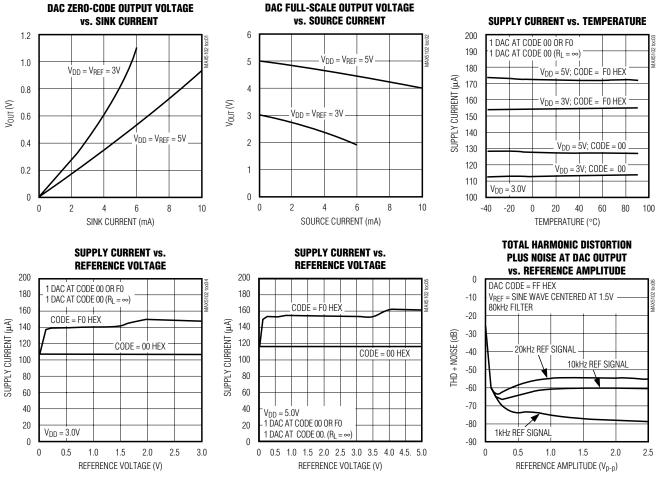


Figure 1. Timing Diagram

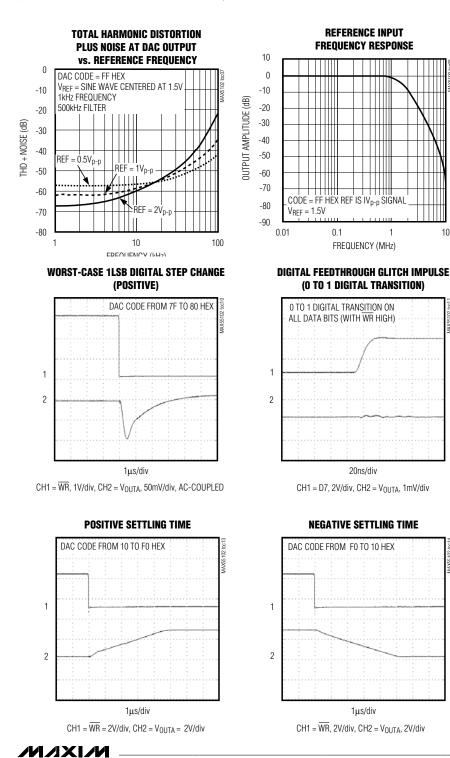


Typical Operating Characteristics (continued)

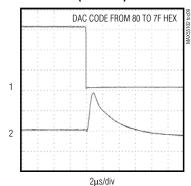
10

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 $(V_{DD} = V_{REF} = +3V, R_L = 10k\Omega, C_L = 100pF, code = FF hex, T_A = +25^{\circ}C, unless otherwise noted.)$

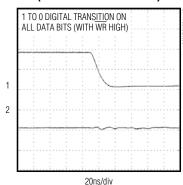


WORST-CASE 1LSB DIGITAL STEP CHANGE (NEGATIVE)



 $CH1 = \overline{WR}$, 1V/div, $CH2 = V_{OUTA}$, 50mV/div, AC-COUPLED

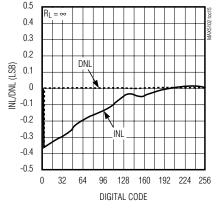
DIGITAL FEEDTHROUGH GLITCH IMPULSE (1 TO 0 DIGITAL TRANSITION)



CH1 = D7, 2V/div, CH2 = V_{OUTA}, 1mV/div

INTEGRAL AND DIFFERENTIAL

NONLINEARITY vs. DIGITAL CODE



MAX5102

Pin Description

PIN	NAME	FUNCTION			
1	1 V _{DD} Positive Supply Voltage. Bypass V _{DD} to GND using a 0.1µF capacitor.				
2	2 REF Reference Voltage Input				
3	3 SHDN Shutdown. Connect SHDN to GND for normal operation.				
4	WR	WR Write Input (active low). Use WR to load data into the DAC input latch selected by A0.			
5–12	D7-D0 Data Inputs				
13	A0 DAC Address Select Bit				
14	14 GND Ground				
15	OUTB DAC B Voltage Output				
16	OUTA	DUTA DAC A Voltage Output			

Detailed Description

Digital-to-Analog Section

The MAX5102 uses a matrix decoding architecture for the DACs. The external reference voltage is divided down by a resistor string placed in a matrix fashion. Row and column decoders select the appropriate tab from the resistor string to provide the needed analog voltages. The resistor network converts the 8-bit digital input into an equivalent analog output voltage in proportion to the applied reference voltage input. The resistor string presents a code-independent input impedance to the reference and guarantees a monotonic output.

These devices can be used in multiplying applications. Their voltages are buffered by rail-to-rail op amps connected in a follower configuration to provide a rail-to-rail output (see *Functional Diagram*).

Low-Power Shutdown Mode

The MAX5102 features a shutdown mode that reduces current consumption to 1nA. A high voltage on the SHDN pin shuts down the DACs and the output amplifiers. In shutdown mode, the output amplifiers enter a high-impedance state. When bringing the device out of shutdown, allow 13µs for the output to stabilize.

Output Buffer Amplifiers

The DAC outputs are internally buffered by precision amplifiers with a typical slew rate of 0.6V/ μ s. The typical settling time to $\pm 1/2$ LSB at the output is 6 μ s when loaded with 10k Ω in parallel with 100pF.

Reference Input

The MAX5102 provides a code-independent input impedance on the REF input. Input impedance is typically 460k Ω in parallel with 15pF, and the reference input voltage range is 0 to V_{DD}. The reference input accepts positive DC signals, as well as AC signals with peak values between 0 and V_{DD}. The voltage at REF sets the full-scale output voltage for the DAC. The output voltage (V_{OUT}) for any DAC is represented by a digitally programmable voltage source as follows:

$$V_{OUT} = (N_B \cdot V_{REF}) / 256$$

where $N_{\mbox{\scriptsize B}}$ is the numeric value of the DAC binary input code.

Digital Inputs and Interface Logic

In the MAX5102, address line A0 selects the DAC that receives data from D0–D7, as shown in Table 1. When WR is low, the addressed DAC's input latch is transparent. Data is latched when WR is high. The DAC outputs (OUTA, OUTB) represent the data held in the two 8-bit

Table 1. MAX5102 Addressing Table(partial list)

WR	A0 LATCH STATE		
Н	Х	Input data latched	
L	L	DAC A input latch transparent	
L	Н	DAC B input latch transparent	

H = High state, L = Low state, X = Don't care



input latches. To avoid output glitches in the MAX5102, ensure that data is valid before \overline{WR} goes low. When the device powers up (i.e., V_{DD} ramps up), all latches are internally preset with code 00 hex.

Applications Information

External Reference

The reference source resistance must be considerably less than the reference input resistance. To keep within 1LSB error in an 8-bit system, R_S must be less than R_{REF}/256. Hence, maintain a value of R_S < 1k Ω to ensure 8-bit accuracy. If V_{REF} is DC only, bypass REF to GND with a 0.1µF capacitor. Values greater than this improve noise rejection.

Power Sequencing

The voltage applied to REF should not exceed V_{DD} at any time. If proper power sequencing is not possible,

connect an external Schottky diode between REF and V_{DD} to ensure compliance with the absolute maximum ratings. Do not apply signals to the digital inputs before the device is fully powered up.

Power-Supply Bypassing and Ground Management

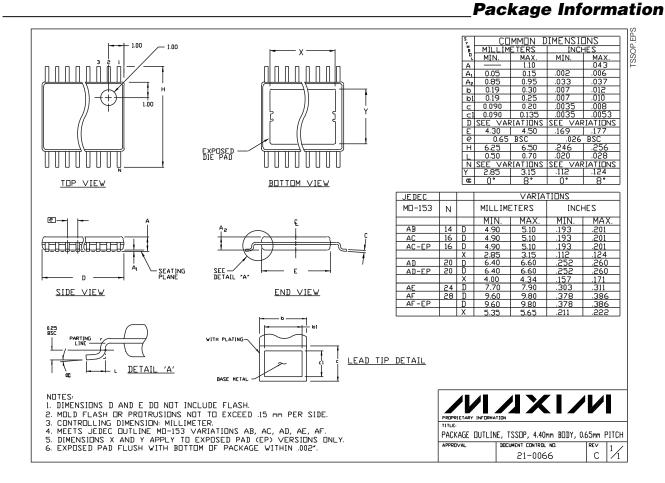
Digital or AC transient signals on GND can create noise at the analog output. Return GND to the highest-quality ground available. Bypass V_{DD} with a 0.1µF capacitor, located as close to V_{DD} and GND as possible.

Careful PC board ground layout minimizes crosstalk between the DAC outputs and digital inputs.

Chip Information

TRANSISTOR COUNT: 6848





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